



SOT505-2

plastic thin shrink small outline package; 8 leads; body width 3 mm; lead length 0.5 mm

8 June 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	TSSOP8
Package type industry code	TSSOP8
Package style descriptive code	TSSOP (thin shrink small outline package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	16-1-2002

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		2.9	-	3	3.1	mm
E	package width		2.9	-	3	3.1	mm
A	seated height		-	-	1.1	1.1	mm
A ₂	package height		0.75	-	0.85	0.95	mm
e	nominal pitch		-	-	0.65	-	mm
n ₂	actual quantity of termination		-	-	8	-	



2. Package outline

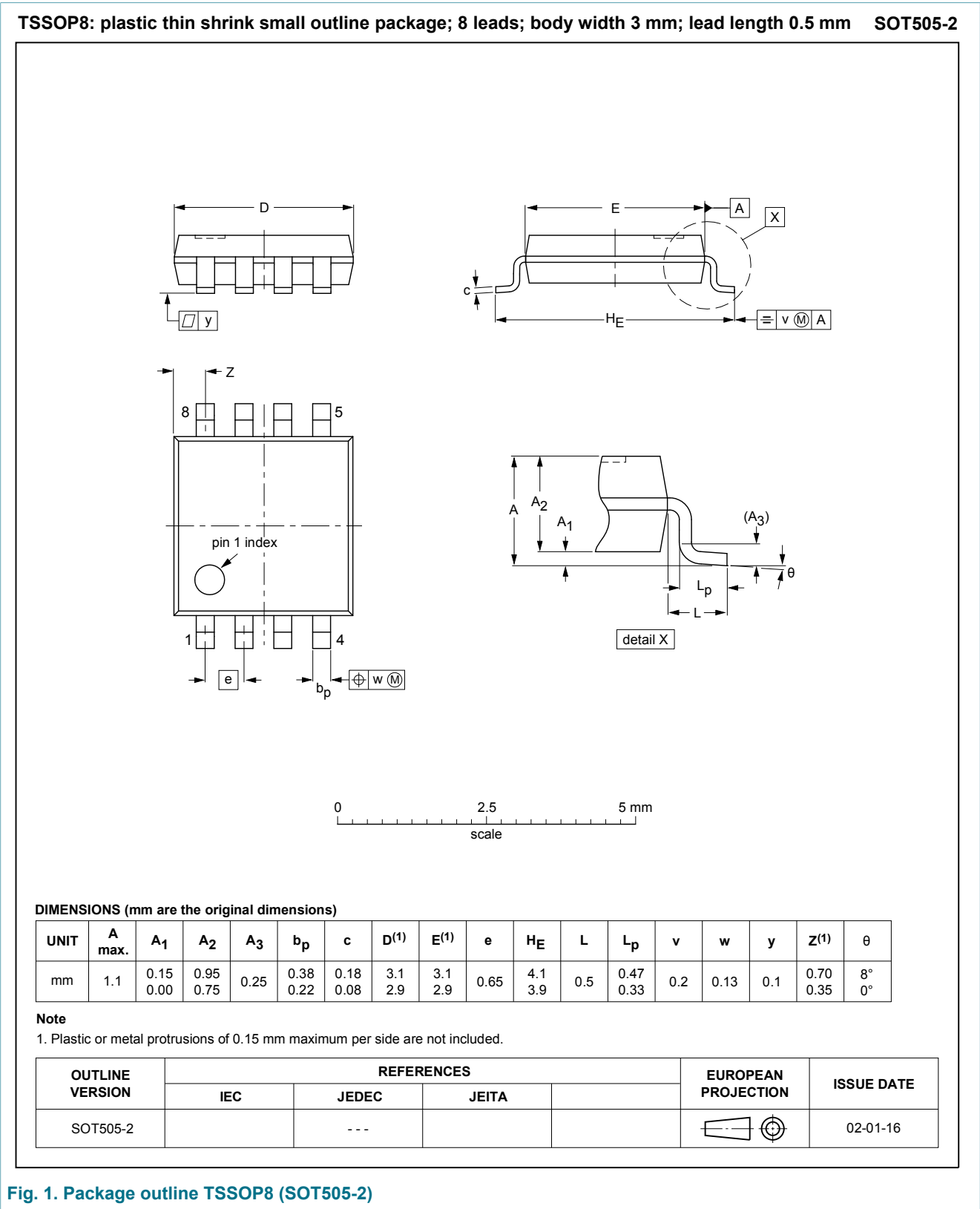


Fig. 1. Package outline TSSOP8 (SOT505-2)

3. Soldering

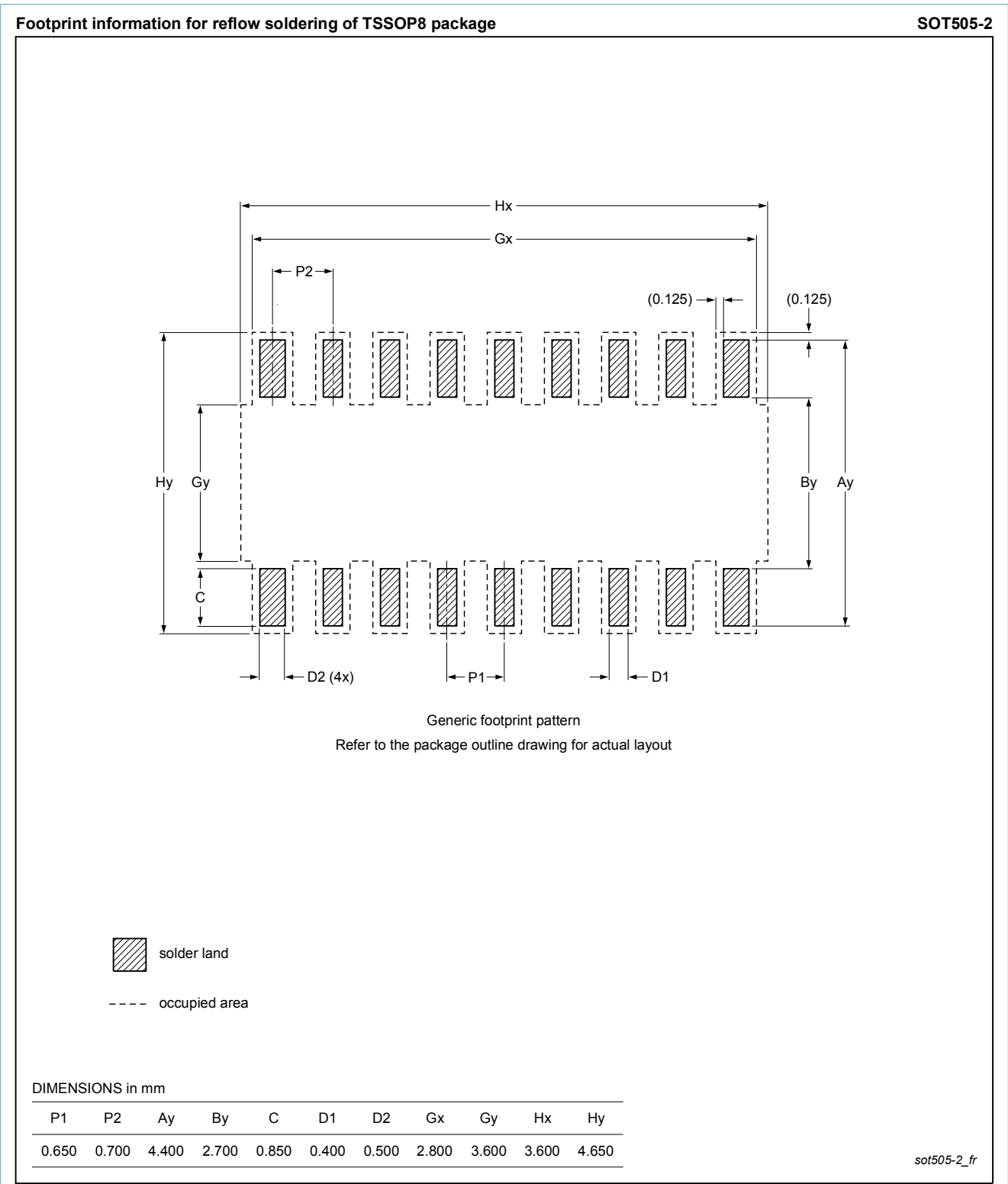


Fig. 2. Reflow soldering footprint for TSSOP8 (SOT505-2)

4. Legal information

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